

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

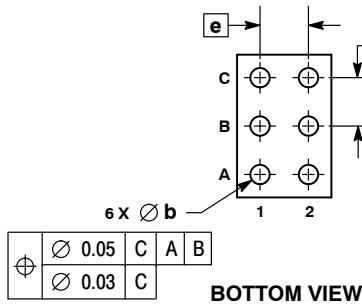
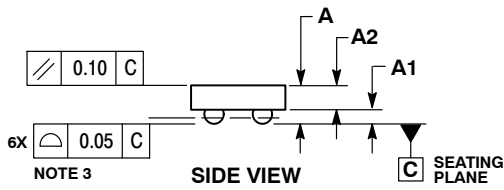
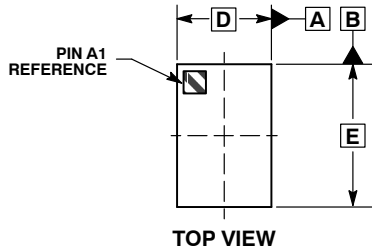
ON Semiconductor®



A1  
SCALE 4:1

6 PIN FLIP-CHIP, 1.6x2.4  
CASE 499BD  
ISSUE A

DATE 14 JAN 2009



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.64
A1	0.22	0.28
A2	0.34	0.36
b	0.29	0.34
D	1.52	1.60
E	2.32	2.40
e	0.80 BSC	

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	6 PIN FLIP-CHIP, 1.6X2.4, 0.8P	PAGE 1 OF 2

